

ABSTRACT

A method for the continuous vacuum cleaning of a substrate, characterized in that:

- a species is chosen that has a low sputtering efficiency and is chemically active with regard to the soiling matter;
- using at least one linear ion source, a plasma is generated from a gas mixture comprising predominantly the species having a low sputtering efficiency, especially one based on oxygen; and
- at least one surface portion of the substrate is subjected to the plasma so that said ionized species at least partly eliminates, by chemical reaction, the soiling matter possibly adsorbed or located on the surface portion.